

## Electronic Patent Application Fee Transmittal

Application Number:	10511566			
Filing Date:	13-Apr-2005			
Title of Invention:	PROCESS OF VAPOR DEPOSITING GLASS LAYERS FOR WAFER-LEVEL HERMETIC ENCAPSULATION OF ELECTRONIC MODULES			
First Named Inventor/Applicant Name:	Jurgen Leib			
Filer:	Charles Nicholas Ruggiero/ruth olivo			
Attorney Docket Number:	2133.063USU			

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1810</b>